# Low-Voltage CMOS Quad 2-Input NAND Gate

#### With 5 V-Tolerant Inputs

The MC74LCX00 is a high performance, quad 2–input NAND gate operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A  $V_{\rm I}$  specification of 5.5 V allows MC74LCX00 inputs to be safely driven from 5 V devices.

Current drive capability is 24 mA at the outputs.

#### **Features**

- Designed for 2.3 V to 3.6 V V<sub>CC</sub> Operation
- 5 V Tolerant Inputs Interface Capability With 5 V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- · 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V
   Machine Model >200 V
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



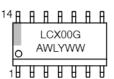
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MARKING DIAGRAMS



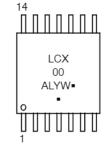
SOIC-14 D SUFFIX CASE 751A





1

TSSOP-14 DT SUFFIX CASE 948G



A = Assembly Location

L, WL = Wafer Lot Y = Year W, WW = Work Week G or • = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

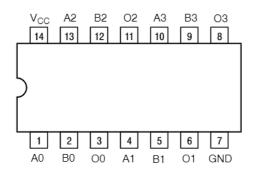


Figure 1. Pinout: 14-lead (Top View)

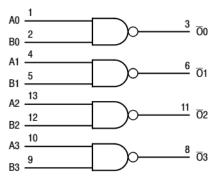


Figure 2. Logic Diagram

#### **PIN NAMES**

Pins	Function		
An, Bn	Data Inputs		
On	Outputs		

#### TRUTH TABLE

In	outs	Outputs
An	Bn	On
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

H = High Voltage Level L = Low Voltage Level

For I<sub>CC</sub> reasons, DO NOT FLOAT Inputs

#### MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \le V_{\parallel} \le +7.0$		V
Vo	DC Output Voltage	$-0.5 \le V_{O} \le V_{CC} + 0.5$	Output in HIGH or LOW State (Note 1)	V
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
lok	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
		+50	Vo > Vcc	mA
I <sub>O</sub>	DC Output Source/Sink Current	±50		mA
Icc	DC Supply Current Per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current Per Ground Pin	±100		mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150		°C
MSL	Moisture Sensitivity		Level 1	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

<sup>1.</sup> IO absolute maximum rating must be observed.

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Туре	Max	Unit
V <sub>CC</sub>	, 0	perating ata Retention Only	2.0 1.5	2.5, 3.3 2.5, 3.3	3.6 3.6	V
VI	Input Voltage		0		5.5	V
V <sub>O</sub>	, ,	HIGH or LOW State) -State)	0		V <sub>CC</sub>	V
I <sub>OH</sub>	V	<sub>CC</sub> = 3.0 V - 3.6 V <sub>CC</sub> = 2.7 V - 3.0 V <sub>CC</sub> = 2.3 V - 2.7 V			-24 -12 -8	mA
I <sub>OL</sub>	V	CC = 3.0 V - 3.6 V CC = 2.7 V - 3.0 V CC = 2.3 V - 2.7 V			+24 +12 +8	mA
T <sub>A</sub>	Operating Free-Air Temperature		-40		+85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate, V <sub>IN</sub> from 0.8	V to 2.0 V, $V_{CC}$ = 3.0 V	0		10	ns/V

#### DC ELECTRICAL CHARACTERISTICS

			T <sub>A</sub> = -40°C		
Symbol	Characteristic	Condition	Min	Max	Unit
V <sub>IH</sub>	HIGH Level Input Voltage (Note 2)	2.3 V ≤ V <sub>CC</sub> ≤ 2.7 V	1.7		٧
		2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V	2.0		1
V <sub>IL</sub>	LOW Level Input Voltage (Note 2)	2.3 V ≤ V <sub>CC</sub> ≤ 2.7 V		0.7	V
		2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V		0.8	1
V <sub>OH</sub>	HIGH Level Output Voltage	2.3 V ≤ V <sub>CC</sub> ≤ 3.6 V; I <sub>OH</sub> = −100 μA	V <sub>CC</sub> - 0.2		٧
		V <sub>CC</sub> = 2.3 V; I <sub>OH</sub> = -8 mA	1.8		1
		V <sub>CC</sub> = 2.7 V; I <sub>OH</sub> = -12 mA	2.2		1
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -18 mA	2.4		1
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -24 mA	2.2		1
V <sub>OL</sub>	LOW Level Output Voltage	2.3 V ≤ V <sub>CC</sub> ≤ 3.6 V; I <sub>OL</sub> = 100 μA		0.2	٧
		V <sub>CC</sub> = 2.3 V; I <sub>OL</sub> = 8 mA		0.6	1
		V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 12 mA		0.4	1
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 16 mA		0.4	1
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 24 mA		0.55	1
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>CC</sub> = 0, V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V		10	μА
I <sub>IN</sub>	Input Leakage Current	V <sub>CC</sub> = 3.6 V, V <sub>IN</sub> = 5.5 V or GND		±5	μА
I <sub>CC</sub>	Quiescent Supply Current	V <sub>CC</sub> = 3.6 V, V <sub>IN</sub> = 5.5 V or GND		10	μА
$\Delta$ I <sub>CC</sub>	Increase in I <sub>CC</sub> per Input	2.3 ≤ V <sub>CC</sub> ≤ 3.6 V; V <sub>IH</sub> = V <sub>CC</sub> - 0.6 V		500	μА

<sup>2.</sup> These values of V<sub>I</sub> are used to test DC electrical characteristics only.

#### AC CHARACTERISTICS ( $t_R$ = $t_F$ = 2.5 ns; $R_L$ = 500 $\Omega$ )

				Limits					
				T <sub>A</sub> = -40°C to +85°C					
			V <sub>CC</sub> = 3.3	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 2.7 \text{ V}$ $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$					
			C <sub>L</sub> = {	50 pF	C <sub>L</sub> =	50 pF	C <sub>L</sub> = 3	30 pF	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub>	Propagation Delay Time	1	1.5	5.5	1.5	6.2	1.5	6.6	ns
t <sub>PHL</sub>	Input-to-Output		1.5	5.5	1.5	6.2	1.5	6.6	
toshl	Output-to-Output Skew			1.0					ns
t <sub>OSLH</sub>	(Note 3)			1.0					

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

#### DYNAMIC SWITCHING CHARACTERISTICS

			T <sub>A</sub> = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V <sub>OLP</sub>	Dynamic LOW Peak Voltage	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		0.8		V
	(Note 4)	$V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$		0.6		V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		-0.8		V
	(Note 4)	$V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$		-0.6		V

Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

#### CAPACITIVE CHARACTERISTICS

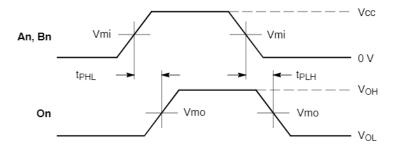
Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 3.3 V, $V_I$ = 0 V or $V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	25	pF

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC74LCX00DG	SOIC-14 (Pb-Free)	55 Units / Rail
MC74LCX00DR2G	SOIC-14 (Pb-Free)	2500 Tape & Reel
MC74LCX00DTG	TSSOP-14 (Pb-Free)	96 Units / Rail
MC74LCX00DTR2G	TSSOP-14 (Pb-Free)	2500 Tape & Reel
NLV74LCX00DTR2G*	TSSOP-14 (Pb-Free)	2500 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

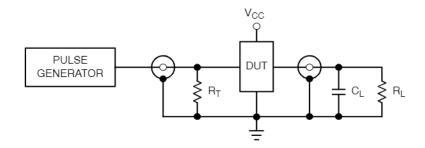


WAVEFORM 1 - PROPAGATION DELAYS

 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$ 

	Vcc				
Symbol	3.3 V ± 0.3 V	2.7 V	2.5 V ± 0.2 V		
Vmi	1.5 V	1.5 V	Vcc/2		
Vmo	1.5 V	1.5 V	Vcc/2		

Figure 3. AC Waveforms



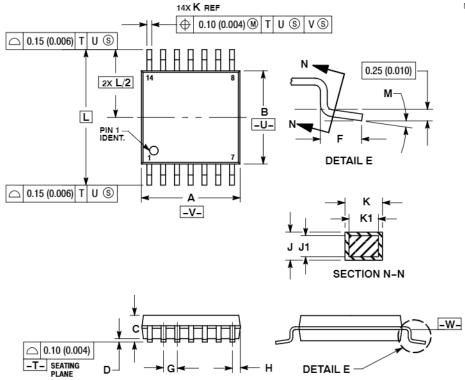
 $C_L$  = 50 pF at  $V_{CC}$  = 3.3  $\pm$  0.3 V or equivalent (includes jig and probe capacitance)  $C_L$  = 30 pF at  $V_{CC}$  = 2.5  $\pm$  0.2 V or equivalent (includes jig and probe capacitance)  $R_L$  =  $R_1$  = 500  $\Omega$  or equivalent

 $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

Figure 4. Test Circuit

#### PACKAGE DIMENSIONS

#### TSSOP-14 CASE 948G ISSUE B



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: MILLIMETER.
  - DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
     MOLD FLASH OR GATE BURRS SHALL NOT

  - MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

    4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

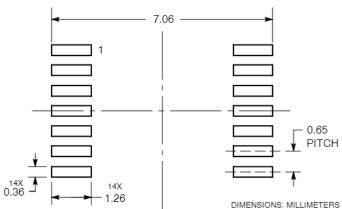
    5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION CONDITION.
    6. TERMINAL NUMBERS ARE SHOWN FOR

  - REFERENCE ONLY.

    7. DIMENSION A AND B ARE TO BE
    DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
Κ	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40	BSC	0.252 BSC		
M	0 °	8 °	0 °	8 °	

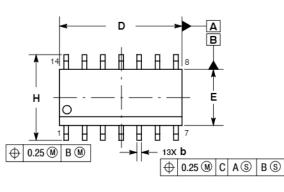
#### SOLDERING FOOTPRINT\*

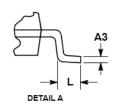


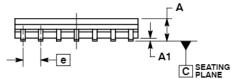
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

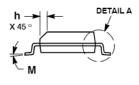
#### PACKAGE DIMENSIONS

#### SOIC-14 NB CASE 751A-03 ISSUE K









#### NOTES:

- DIMENSIONING AND TOLERANCING PER
  ASME V14 5M 1994
- ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.
- 2. JOHNSION & DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE PROTRUSION
  SHALL BE 0.13 TOTAL IN EXCESS OF AT
  MAXIMUM MATERIAL CONDITION.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
- MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.35	1.75	0.054	0.068
Α1	0.10	0.25	0.004	0.010
<b>A</b> 3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
е	1.27	BSC	0.050 BSC	
Н	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0 °	7°	0°	7°

## 

DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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